NCE N-Channel Enhancement Mode Power MOSFET

Description

The NCE6050I uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

General Features

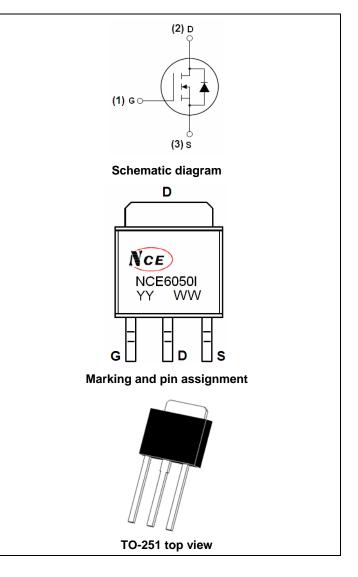
- V_{DS} =60V, I_{D} =50A $R_{DS(ON)}$ <20m Ω @ V_{GS} =10V
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E_{AS}
- Excellent package for good heat dissipation
- Special process technology for high ESD capability

Application

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply

100% UIS TESTED!

100% ΔVds TESTED!



Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCE6050I	NCE6050I	TO-251	-	-	-

Absolute Maximum Ratings (T_C=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	VDS	60	V	
Gate-Source Voltage	Vgs	±20	V	
Drain Current-Continuous	I _D	50	А	
Drain Current-Continuous(T _C =100 °C)	I _D (100℃)	35	Α	
Pulsed Drain Current	I _{DM}	220	А	
Maximum Power Dissipation	P _D	80	W	
Derating factor		0.53	W/°C	
Single pulse avalanche energy (Note 5)	E _{AS}	115	mJ	
Operating Junction and Storage Temperature Range	T_{J}, T_{STG}	-55 To 175	$^{\circ}$	

NCE6050I

Thermal Characteristic

Thermal Resistance, Junction-to-Case ^(Note 2)	$R_{ heta JC}$	1.88	°C/W	
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Electrical Characteristics (T_C=25°C unless otherwise noted)

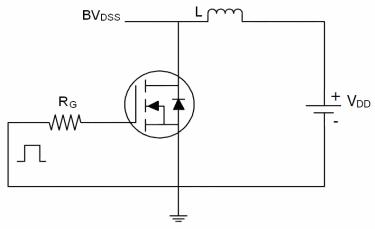
Parameter	Parameter Symbol Condition		Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	60	70	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =60V,V _{GS} =0V	-	-	1	μΑ
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)	<u>.</u>		•			
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$, $I_{D}=250\mu A$	1.5	2.0	2.5	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =20A	-	17	20	mΩ
Forward Transconductance	g Fs	V _{DS} =25V,I _D =20A	24	-	-	S
Dynamic Characteristics (Note4)			•			•
Input Capacitance	C _{lss}	\/ -05\/\/ -0\/	-	900	-	PF
Output Capacitance	Coss	$V_{DS}=25V,V_{GS}=0V,$	-	104	-	PF
Reverse Transfer Capacitance	C _{rss}	F=1.0MHz	-	33	-	PF
Switching Characteristics (Note 4)	<u>.</u>		•			
Turn-on Delay Time	t _{d(on)}		-	25	-	nS
Turn-on Rise Time	t _r	V_{DD} =30V, I_D =2A, R_L =15 Ω	-	5	-	nS
Turn-Off Delay Time	$t_{d(off)}$	V_{GS} =10 V , R_{G} =2.5 Ω	-	50	-	nS
Turn-Off Fall Time	t _f		-	6	-	nS
Total Gate Charge	Qg	\/ 00\/ L 50A	-	30		nC
Gate-Source Charge	Q _{gs}	$V_{DS}=30V,I_{D}=50A,$ $V_{GS}=10V$	-	10		nC
Gate-Drain Charge	Q _{gd}	V _{GS} =10V	-	5		nC
Drain-Source Diode Characteristics	<u>.</u>		•			
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =40A	-		1.2	V
Diode Forward Current (Note 2)	Is		-	-	50	Α
Reverse Recovery Time	t _{rr}	TJ = 25°C, IF = 40A	-	50	-	nS
Reverse Recovery Charge	Qrr	di/dt = 100A/µs ^(Note3)	-	100	-	nC
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				
	I	<u> </u>	•			-

Notes:

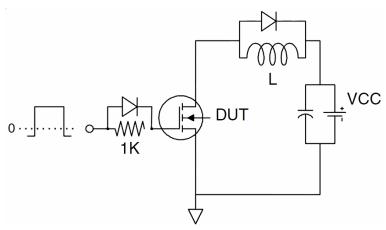
- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- 3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production
- 5. EAS condition:Tj=25 $^{\circ}\!\!\mathrm{C}$,V_DD=30V,V_G=10V,L=0.5mH,Rg=25 $\!\Omega$

Test Circuit

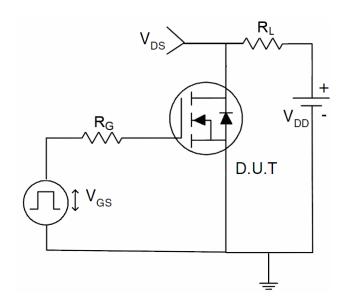
1) E_{AS} Test Circuit



2) Gate Charge Test Circuit



3) Switch Time Test Circuit





Typical Electrical and Thermal Characteristics (Curves)

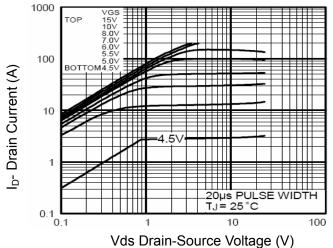


Figure 1 Output Characteristics

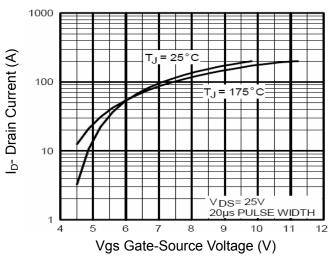


Figure 2 Transfer Characteristics

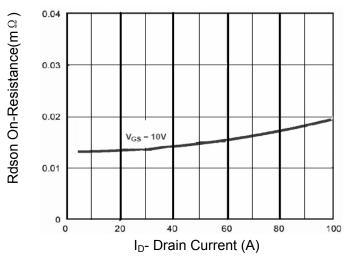


Figure 3 Rdson- Drain Current

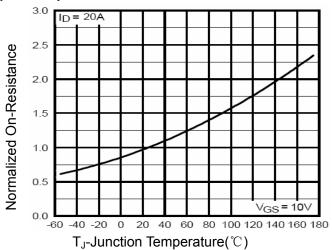


Figure 4 Rdson-JunctionTemperature

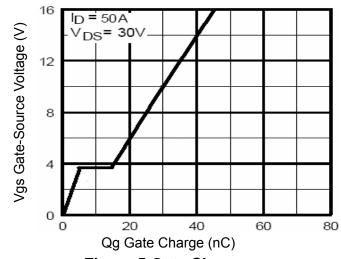


Figure 5 Gate Charge

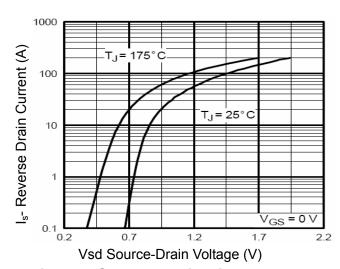


Figure 6 Source- Drain Diode Forward



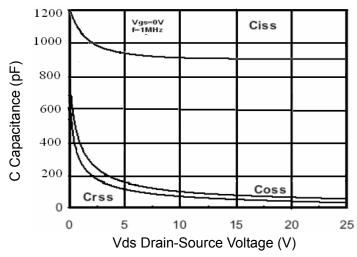


Figure 7 Capacitance vs Vds

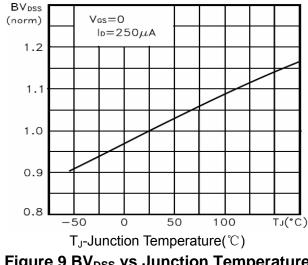


Figure 9 BV_{DSS} vs Junction Temperature

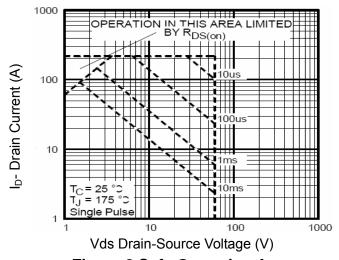


Figure 8 Safe Operation Area

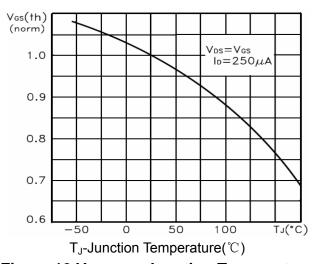


Figure 10 V_{GS(th)} vs Junction Temperature

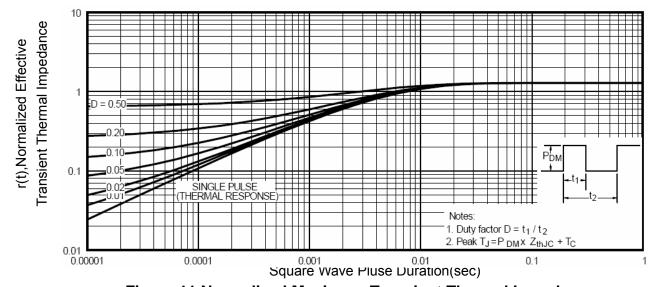
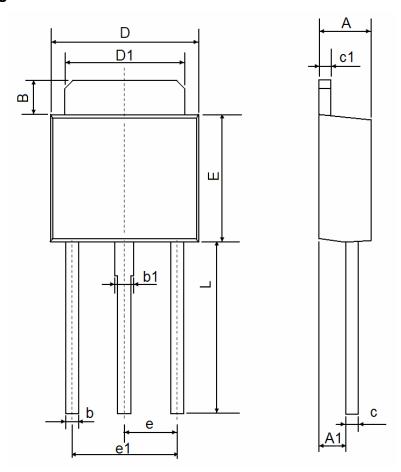


Figure 11 Normalized Maximum Transient Thermal Impedance

TO-251 Package Information



Symbol	Dimensions	In Millimeters	Dimensions In Inches		
	Min.	Max.	Min.	Max.	
А	2.200	2.400	0.087	0.094	
A1	1.050	1.350	0.042	0.054	
В	1.350	1.650	0.053	0.065	
b	0.500	0.700	0.020	0.028	
b1	0.700	0.900	0.028	0.035	
С	0.430	0.580	0.017	0.023	
c1	0.430	0.580	0.017	0.023	
D	6.350	6.650	0.250	0.262	
D1	5.200	5.400	0.205	0.213	
E	5.400	5.700	0.213	0.224	
е	2.300 TYP		0.091	TYP	
e1	4.500	4.700	0.177	0.185	
L	7.500	7.900	0.295	0.311	

http://www.ncepower.com

NCE6050I

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